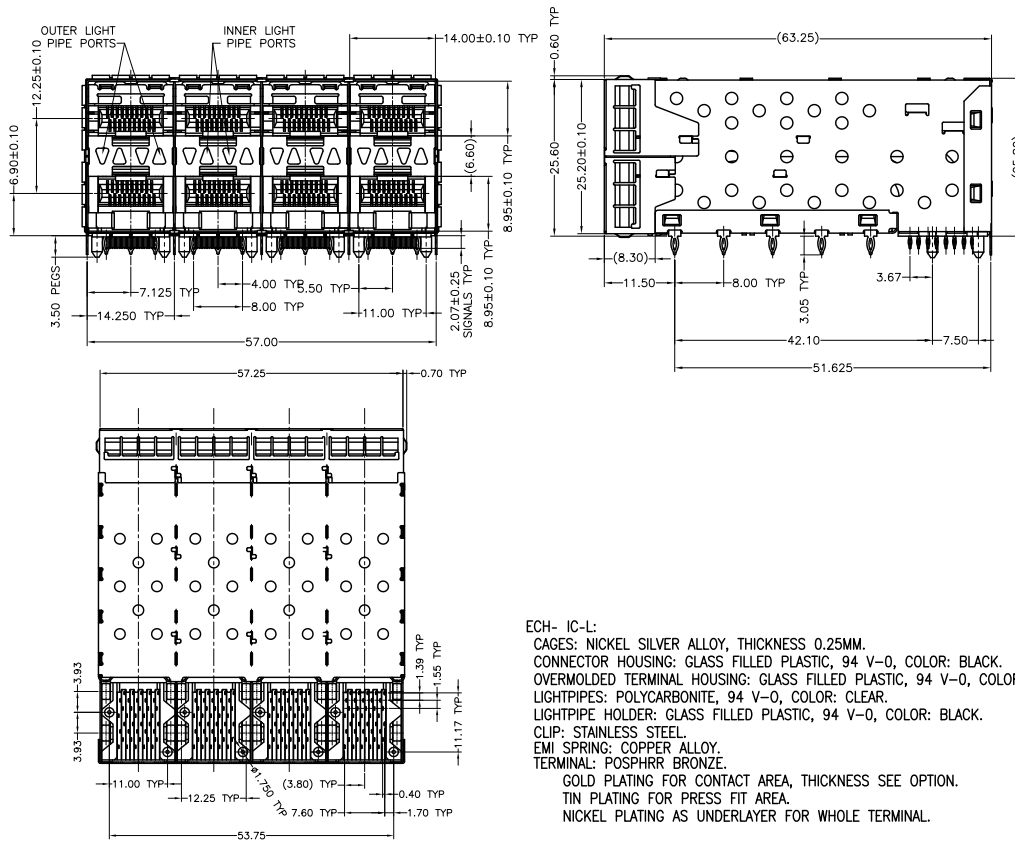
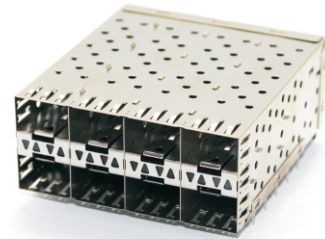


SFP*XFP*QSFP/QSFP+ Connectors

KLS12-SFP+08

Electrical Specifications:

VOLTAGE: 30 VOLTS AC.
CURRENT: 0.50 A PER CONTACT.
CONTACT RESISTANCE:50 MILLIOHMS MAX;
INSULATION RESISTANCE:1000 MEGAOHMS MIN
AT 100 VDC FOR 1 MINUTE.
DIELECTRIC WITHSTANDING VOLTAGE:300 VDC MIN;
TEMPERATURE:
OPERATION: -40°C~+85°C
STORAGE: -55°C~+105°C
LIGHTPIPE PAD LAYOUT IS FOR LOW-PROFILE LED PACKAGE.
LED SIZE(LxWxH): 2x1x0.4MM MAX.
RoHS COMPLIANCE.



ECH- IC-L:
CAGES: NICKEL SILVER ALLOY, THICKNESS 0.25MM.
CONNECTOR HOUSING: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
OVERMOLDED TERMINAL HOUSING: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
LIGHTPIPES: POLYCARBONITE, 94 V-0, COLOR: CLEAR.
LIGHTPIPE HOLDER: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
CLIP: STAINLESS STEEL.
EMI SPRING: COPPER ALLOY.
TERMINAL: POSPHRR BRONZE.
GOLD PLATING FOR CONTACT AREA, THICKNESS SEE OPTION.
TIN PLATING FOR PRESS FIT AREA.
NICKEL PLATING AS UNDERLAYER FOR WHOLE TERMINAL.

ORDER INFORMATION

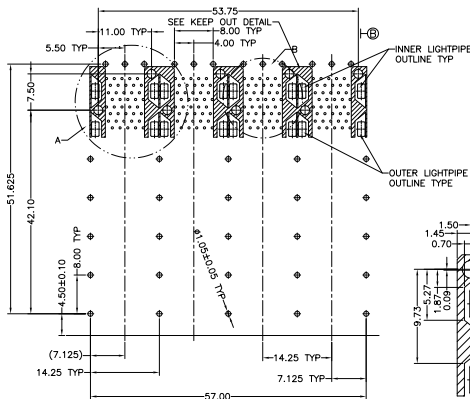
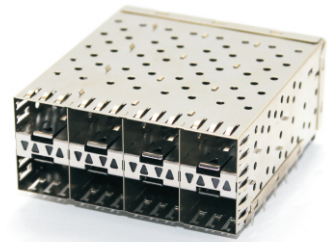
KLS12-SFP+08

Part Number

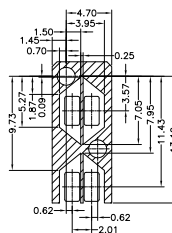
SFP*XFP*QSFP/QSFP+ Connectors

KLS12-SFP+08

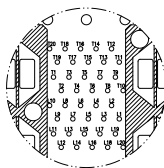
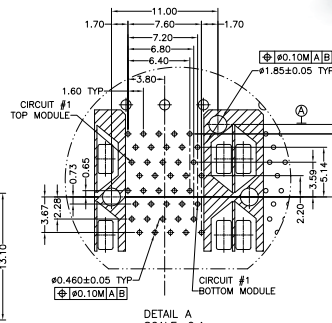
XII



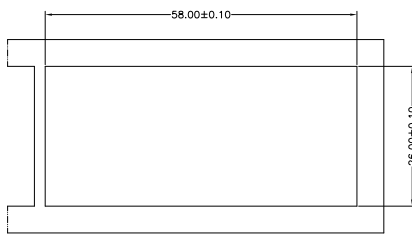
RECOMMENDED PCB LAYOUT—COMPONENT SIDE
PCB THICKNESS 1.6MM MIN
TOLERANCE: ±0.05 MM



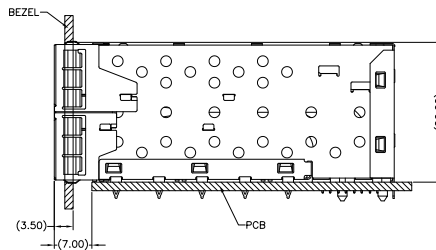
KEEP OUT ZONE DETAIL
SCALE: 2:1



CONNECTOR PIN—OUT DETAIL
COMPONENT SIDE OF BOARD
DETAIL B
SCALE: 2:1



RECOMMENDED BEZEL CUT—OUT CENTER DETAIL
BEZEL THICKNESS 0.8~2.6MM



ORDER INFORMATION

KLS12-SFP+08

Part Number